

SOT1048-1

plastic thin fine-pitch ball grid array package; 296 balls

8 February 2016

Package information

1. Package summary

Terminal position code	B (bottom)
Package type descriptive code	TFBGA296
Package type industry code	TFBGA296
Package style descriptive code	TFBGA (thin fine-pitch ball grid array)
Package style suffix code	NA (not applicable)
Package body material type	P (plastic)
JEDEC package outline code	MO-216
Mounting method type	S (surface mount)
Issue date	2-11-2007

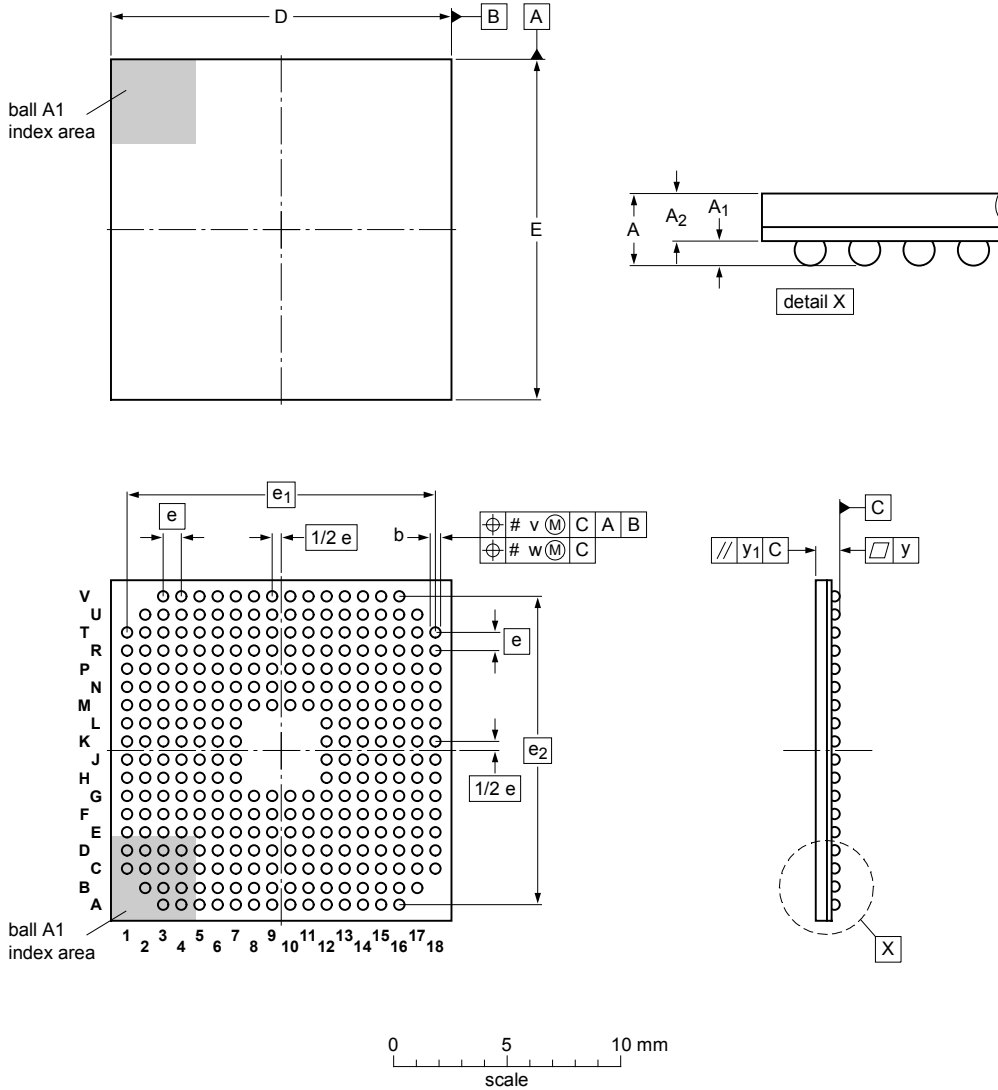
Table 1. Package summary

Symbol	Parameter	Min	Typ	Nom	Max	Unit
D	package length	14.9	-	15	15.1	mm
E	package width	14.9	-	15	15.1	mm
A	seated height	[tbd]	-	1.2	1.2	mm
A ₂	package height	0.65	-	0.725	0.8	mm
n ₂	actual quantity of termination	-	-	296	-	



2. Package outline

TFBGA296: plastic thin fine-pitch ball grid array package; 296 balls SOT1048-1



DIMENSIONS (mm are the original dimensions)

UNIT	A _{max}	A ₁	A ₂	b	D	E	e	e ₁	e ₂	v	w	y	y ₁
mm	1.2	0.4 0.3	0.80 0.65	0.5 0.4	15.1 14.9	15.1 14.9	0.8	13.6	13.6	0.15	0.08	0.12	0.1

OUTLINE VERSION	REFERENCES				EUROPEAN PROJECTION	ISSUE DATE
	IEC	JEDEC	JEITA			
SOT1048-1		MO-216				07-10-19 07-11-02

Fig. 1. Package outline TFBGA296 (SOT1048-1)

3. Legal information

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